

LTspice Model

LDO

ON Semiconductor

NCV8537ML330R2G

Model Information

Model A macro model
Call Name MDC_NCV8537ML330R2G_LT
Pin Assign 1:VOUT 2:VOUT 3:SENSE 4:GND 5:PWRG 6:NC 7:NR 8:_SD 9:VIN 10:VIN 11:EPAD
File List Model Library MDC_NCV8537ML330R2G_LT01.lib
 Model Report MDC_NCV8537ML330R2G_LT.pdf(this file)
Verified Simulator Version Ltspice XVII

Note

References

The information which was used for modeling is as follow:

[Data Sheet]

- Date/Version October, 2019 – Rev. 6
- Product name NCV8537ML330R2G
- Company name ON Semiconductor

[Characteristics listed]

- Characteristics VIN-VOUT, Vdrop, Ilimit, Line-Reg, Load-Reg, Shutdown, Power good

Simulation Condition

This table shows the range of evaluated simulation range that was not occurs any convergence problems in this area.

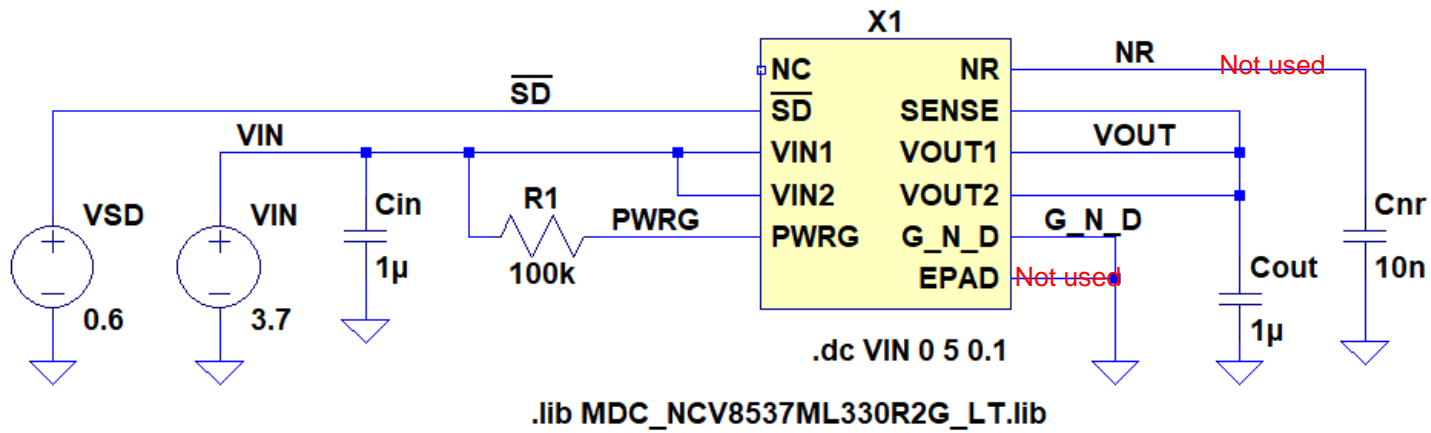
| Item | Condition | Unit |
|-------------|-----------|-------|
| Temperature | 25 | deg C |

Model Functions Table

| Functions- | Implemented |
|------------------|-------------|
| VIN-VOUT(3.3V) | ○ |
| Vdrop | ○ |
| Ilimit | ○ |
| Line-Reg | ○ |
| Load-Reg | ○ |
| Ripple-Rejection | ○ |
| SENSE | ○ |
| Shutdown | ○ |
| Power good | ○ |
| Noise Reduction | - |
| Exposed thermal | - |

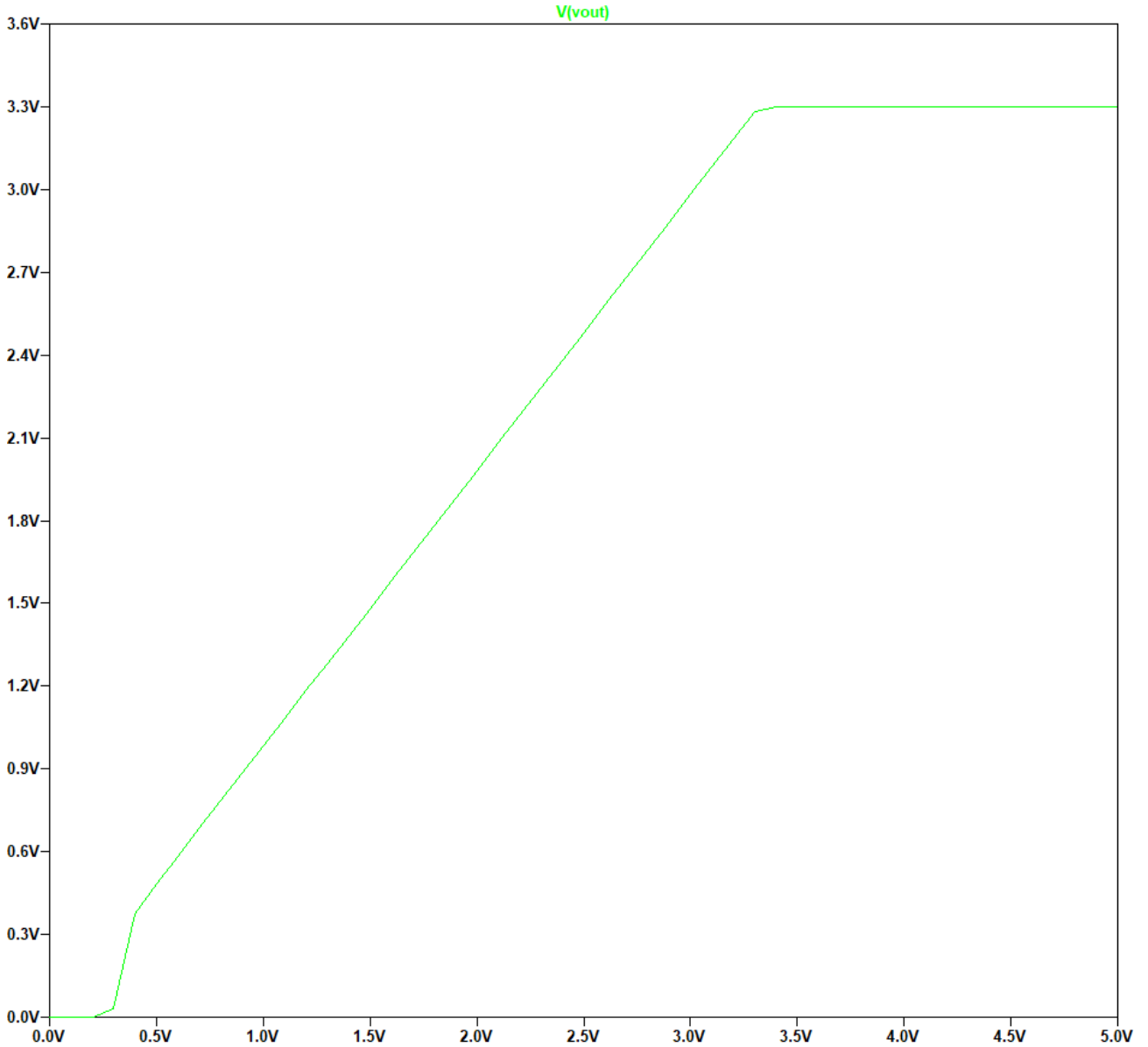
VIN-VOUT Testbench

Referred to Data Sheet



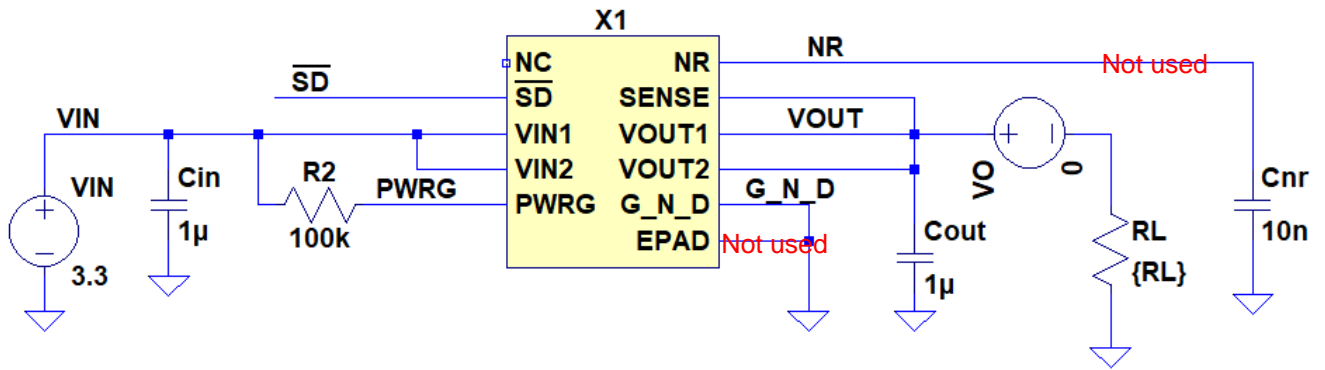
Simulation results are following.
Explanatory notes — : simulated

VIN-VOUT



Vdrop Testbench

Referred to Data Sheet

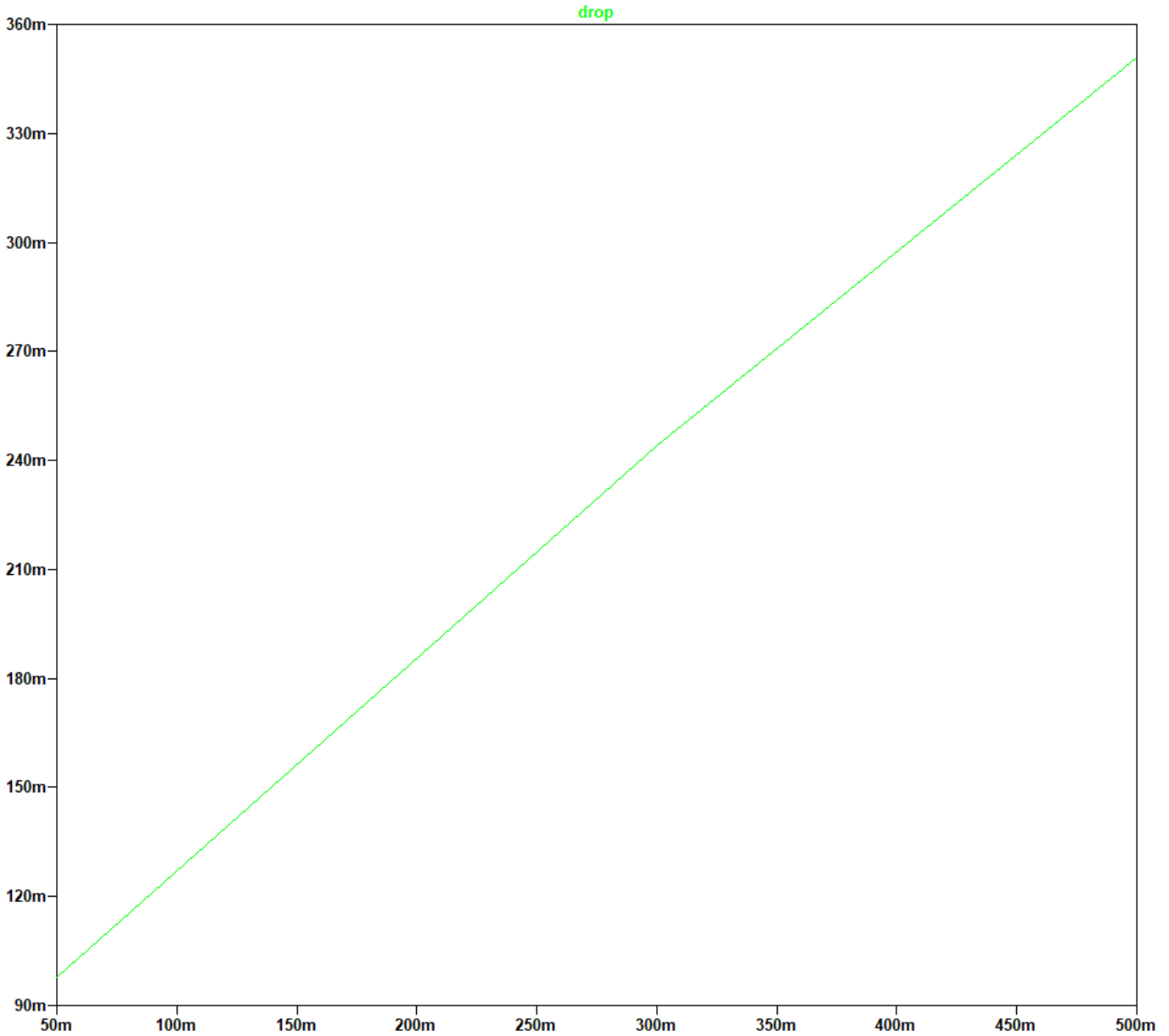


```

.dc VIN 0 5 0.1
.param RL=VOUT/IOUT VOUT=3.3 IOOUT=0.5
.step param IOOUT list 50m 300m 500m
.meas DC iload FIND I(VOUT) AT 3.2
.meas DC drop FIND V(VIN)-V(VOUT) WHEN V(VOUT)=3.2 RISE=1
.lib MDC_NCV8537ML330R2G_LT.lib
    
```

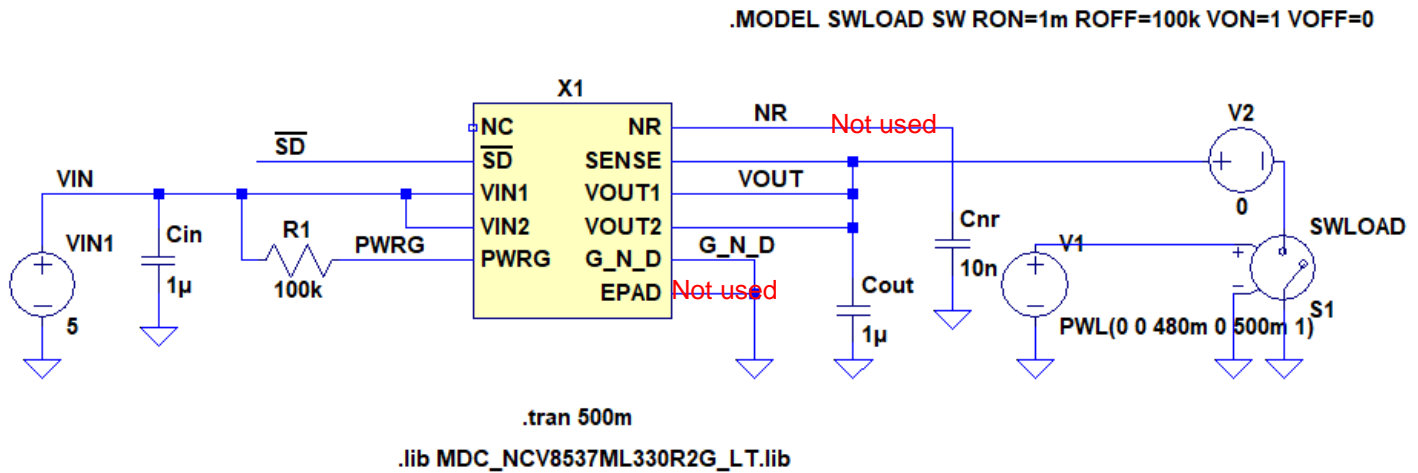
Simulation results are following.
Explanatory notes — : simulated

Vdrop



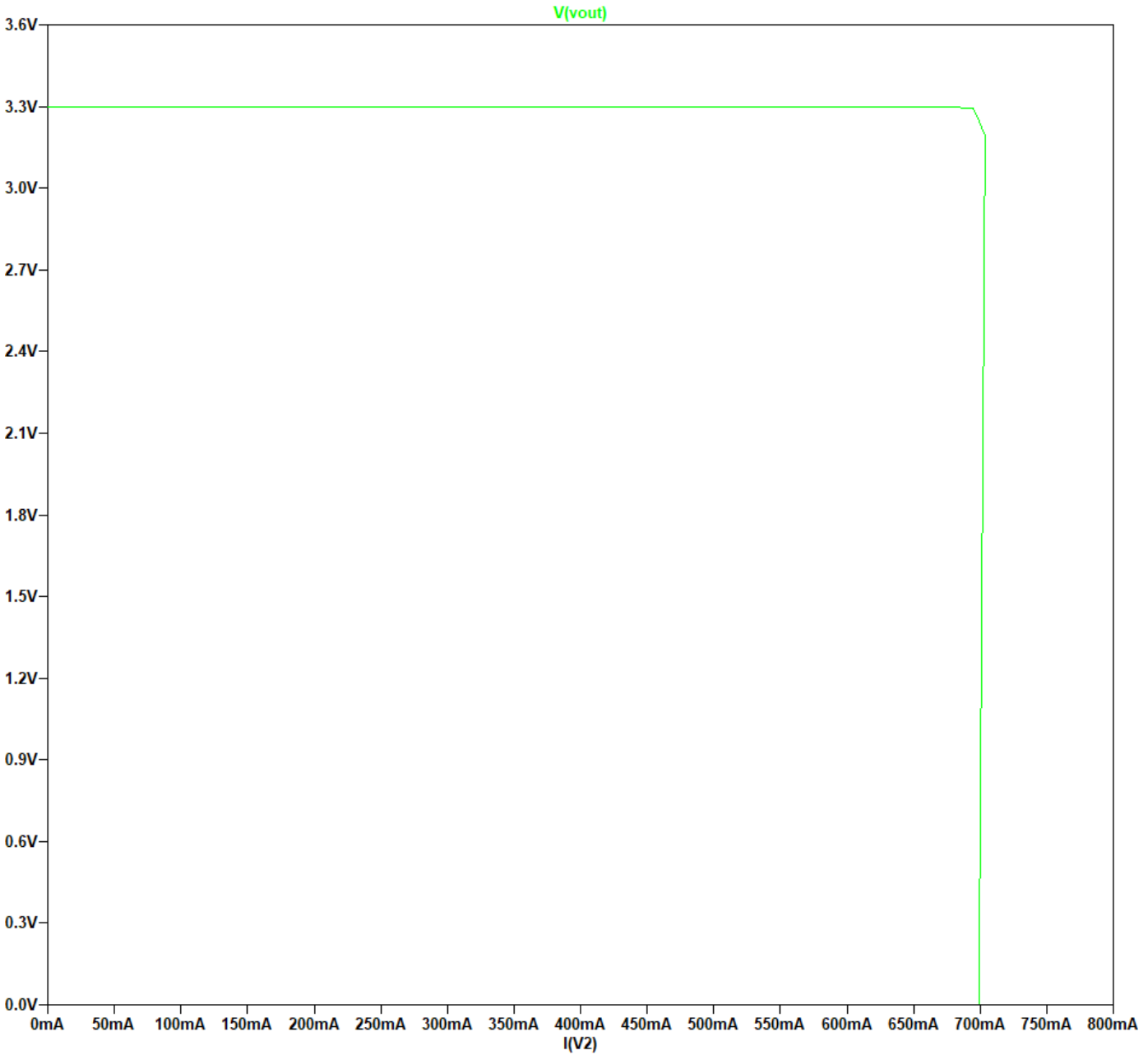
Ilimit Testbench

Referred to Data Sheet



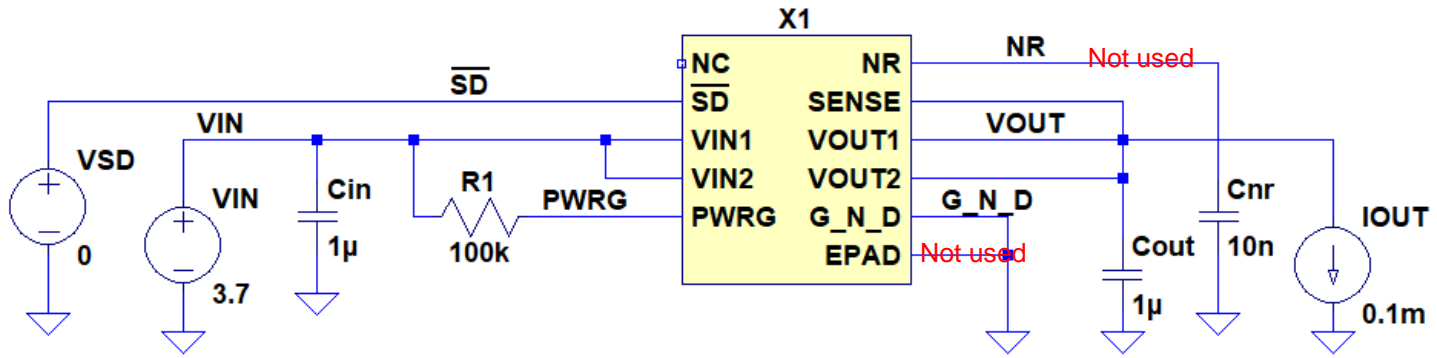
Simulation results are following.
Explanatory notes — : simulated

Ilimit



Line-Reg Testbench

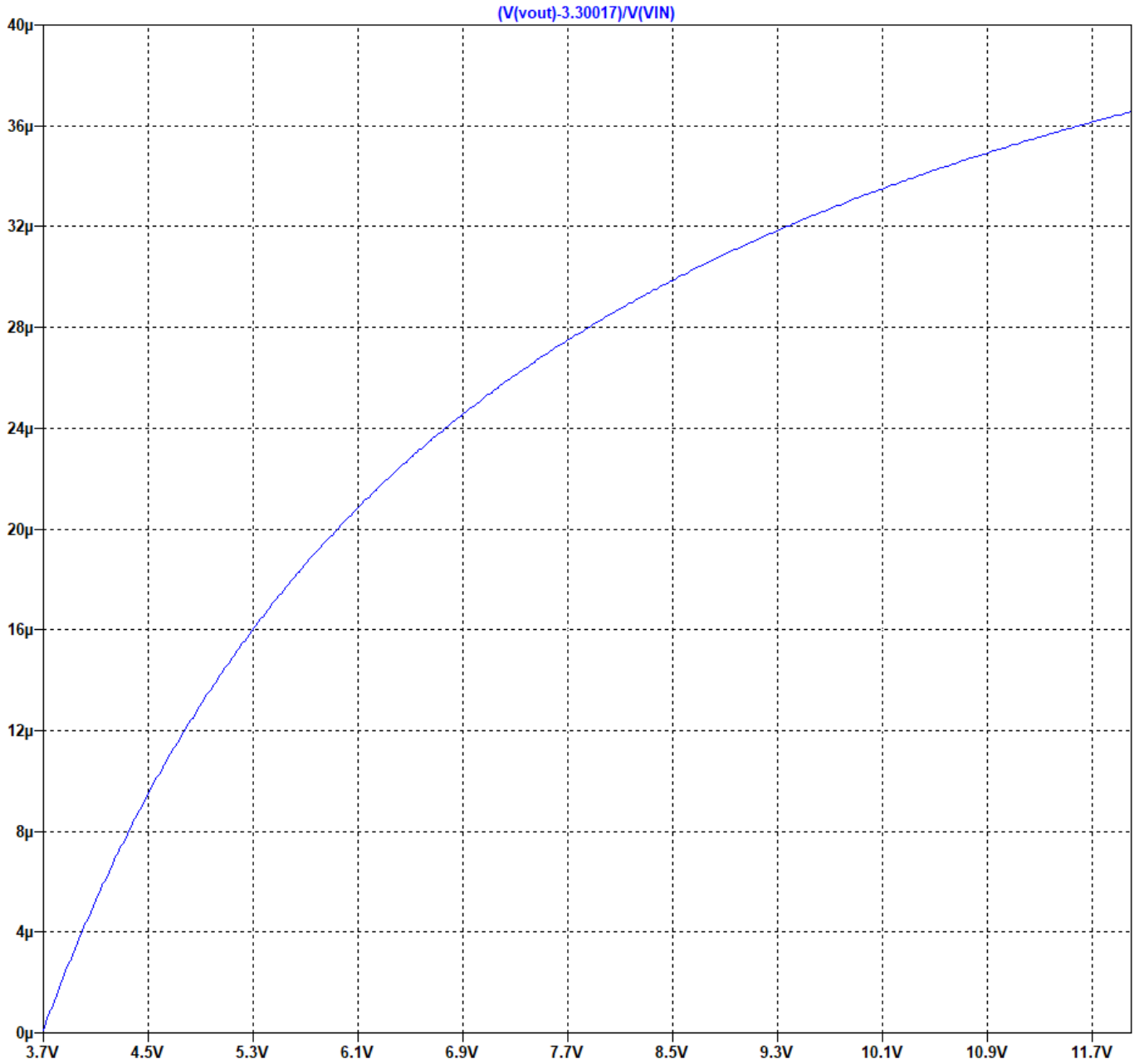
Referred to Data Sheet



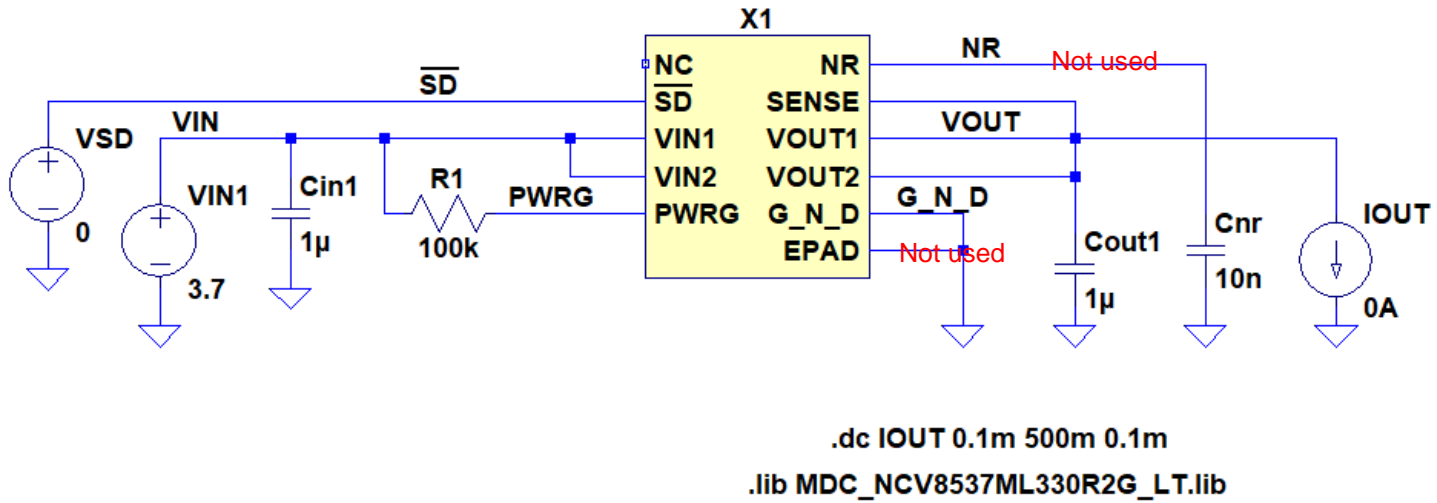
```
.dc VIN 3.7 12 0.01
.lib MDC_NCV8537ML330R2G_LT.lib
```

Simulation results are following.
Explanatory notes — : simulated

Line-Reg

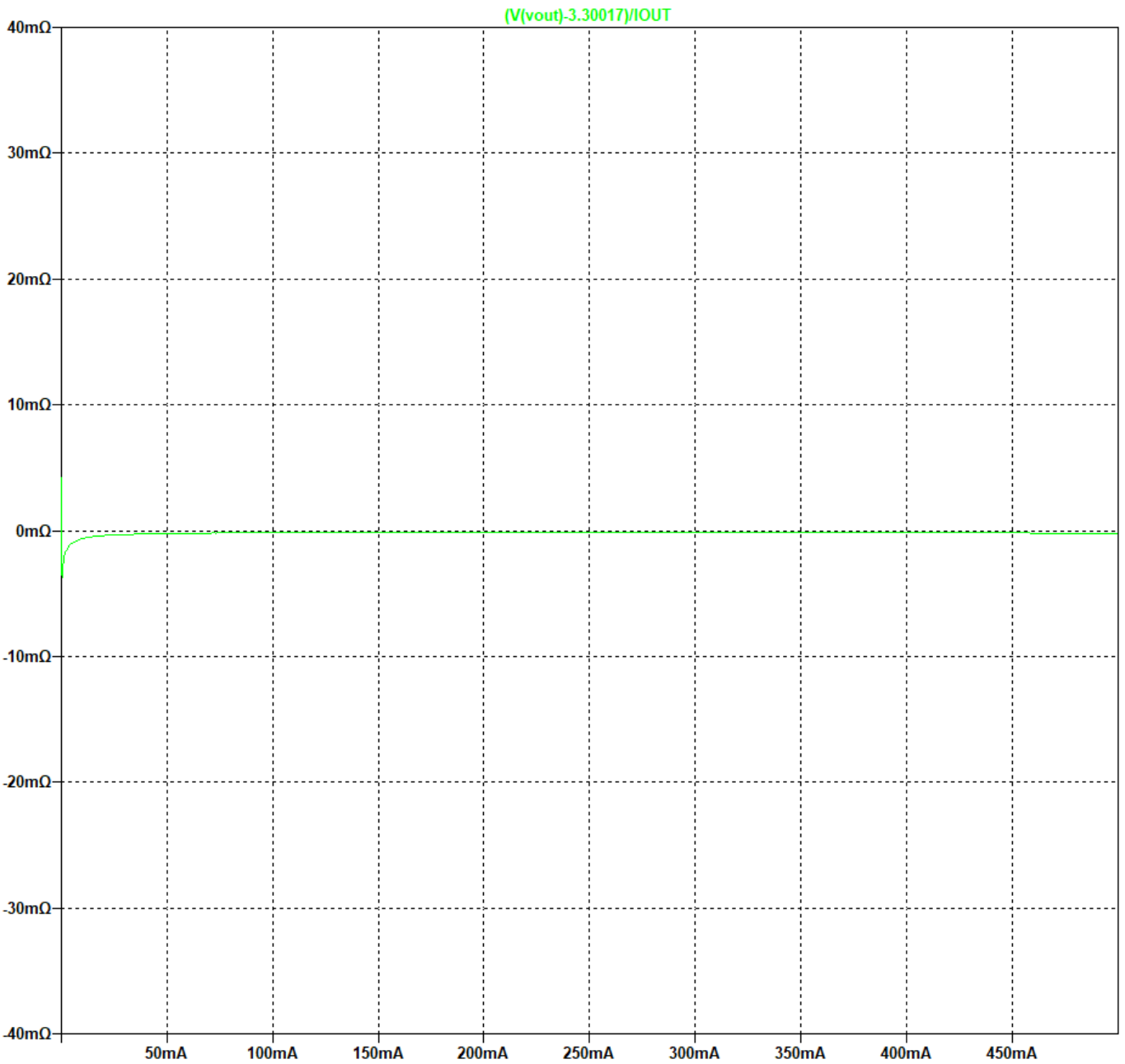


Load-Reg Testbench
Referred to Data Sheet



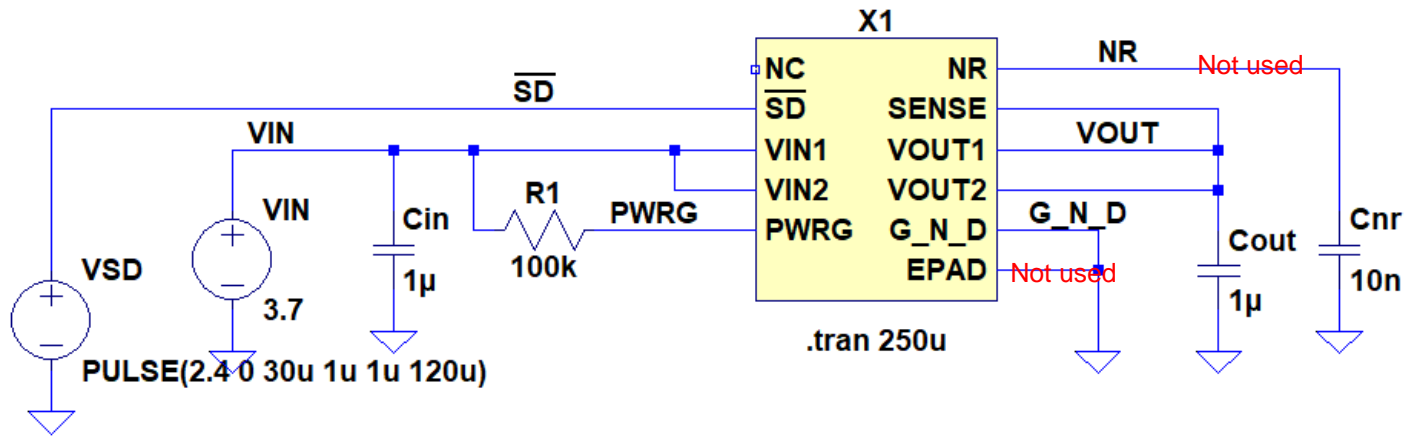
Simulation results are following.
Explanatory notes — : simulated

Load-Reg



Shutdown/Power good Testbench

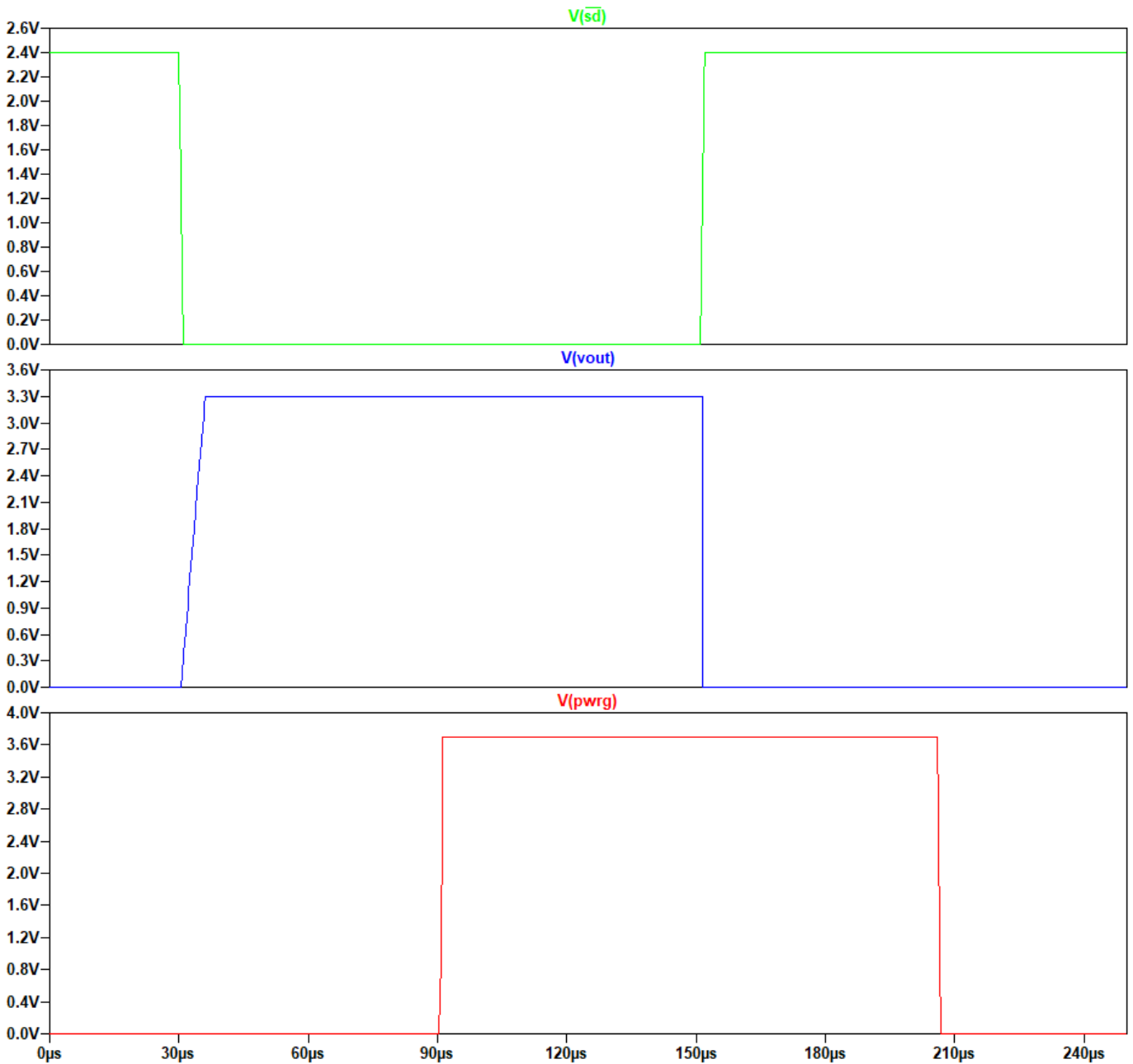
Referred to Data Sheet



```
.meas TRAN ON TRIG V(vout)=1.65 RISE=1 TARG V(pwrg)=3.35 RISE=1
.meas TRAN OFF TRIG V(vout)=1.65 FALL=1 TARG V(pwrg)=3.35 FALL=1
.lib MDC_NCV8537ML330R2G_LT.lib
```

Simulation results are following.
Explanatory notes — : simulated

Shutdown/Power good



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